

DC Input, Random-Phase Photo TRIAC Coupler

Description

The SL301X, SL302X and SL305X series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP6 package with different lead forming options. With the robust coplanar double mold structure, SL301X, SL302X and SL305X series provide the most stable isolation feature.

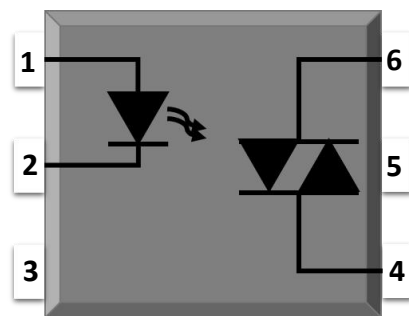
Features

- High isolation 5000 VRMS
- DC input with random-phase photo triac output
- Operating temperature range - 40 °C to 100 °C
- REACH & RoHS compliance
- MSL class 1
- Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC - GB4943.1, GB8898
 - cUL- CSA Component Acceptance Service Notice No. 5A

Applications

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

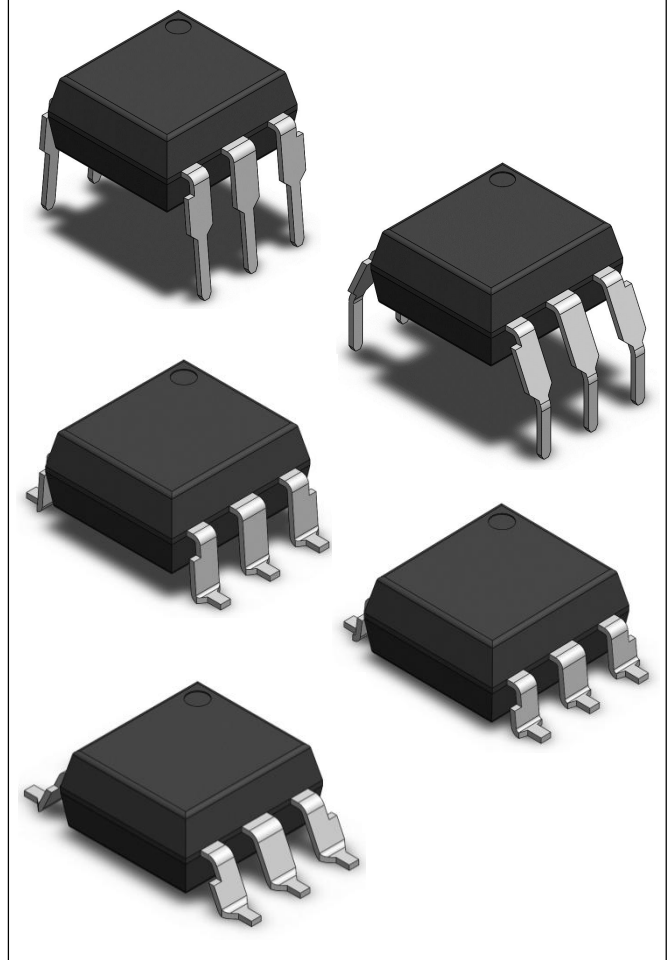
SCHEMATIC



PIN DEFINITION

- | | |
|------------|--------------|
| 1. Anode | 4. Terminal |
| 2. Cathode | 5. Substrate |
| 3. NC | 6. Terminal |

PACKAGE OUTLINE



ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	VALUE	UNIT	NOTE
INPUT					
Forward Current		I_F	60	mA	
Reverse Voltage		V_R	6	V	
Junction Temperature		T_j	125	°C	
Input Power Dissipation		P_i	100	mW	
OUTPUT					
Off-state Output Terminal Voltage	SL301X	V_{DRM}	250	V	
	SL302X		400		
	SL305X		600		
Peak Repetitive Surge Current PW=100μs, 120pps		I_{TSM}	1	A	
Junction Temperature		T_j	125	°C	
Output Power Dissipation		P_o	300	mW	
COMMON					
Total Power Dissipation		P_{tot}	400	mW	
Isolation Voltage		V_{iso}	5000	Vrms	1
Operating Temperature		T_{opr}	-40~100	°C	
Storage Temperature		T_{stg}	-55~125	°C	
Soldering Temperature		T_{sol}	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V _F	-	1.24	1.4	V	I _F =10mA	
Reverse Current	I _R	-	-	10	μA	V _R =6V	
Input Capacitance	C _{in}	-	8.5	250	pF	V=0, f=1kHz	
OUTPUT							
Peak Off-state Current, Either Direction	I _{DRM}	-	-	100	nA	V _{DRM} =Rated V _{DRM} I _F =0	3
Peak On-state Current, Either Direction	V _{TM}	-	1.58	2.5	V	I _{TM} =100mA	
Critical Rate of Rise of Off-state Voltage	dV/dt	1000	-	-	V/μs	V _{PEAK} =Rated V _{DRM}	4
TRANSFER CHARACTERISTICS							
LED	SL3010,SL3021, SL3051	I _{FT}	-	-	15	mA	Terminal Voltage = 3V I _{TM} =100mA
Trigger	SL3011,SL3022, SL3052		-	-	10		
Current	SL3012,SL3023, SL3053		-	-	5		
Holding Current	I _H	-	257	-	μA		
Isolation Resistance	R _{iso}	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C _{IO}	-	0.8	-	pF	V=0, f=1MHz	

Note3. Test voltage must be applied within dV/dt rating.

Note4. Refer to Fig.15 & Fig.16

CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Ambient Temperature

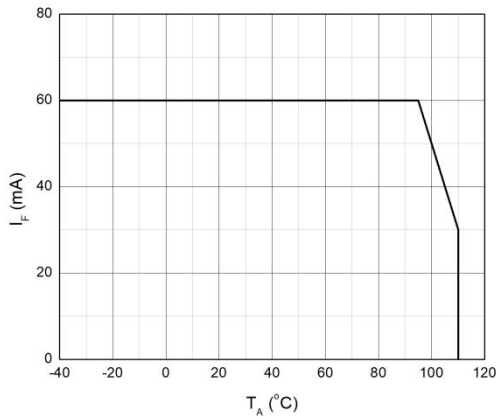


Fig.2 On-state Terminal Current vs. Ambient Temperature

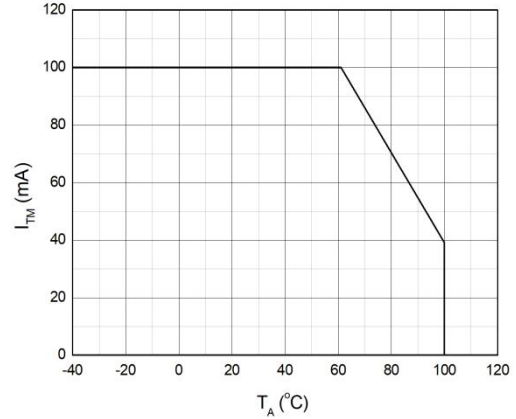


Fig.3 Forward Current vs. Forward Voltage

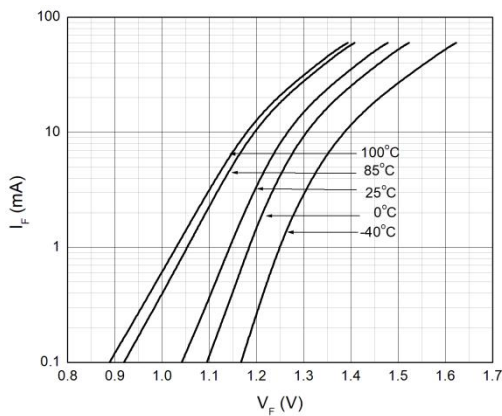


Fig.4 Off-state Terminal Current vs. Ambient Temperature

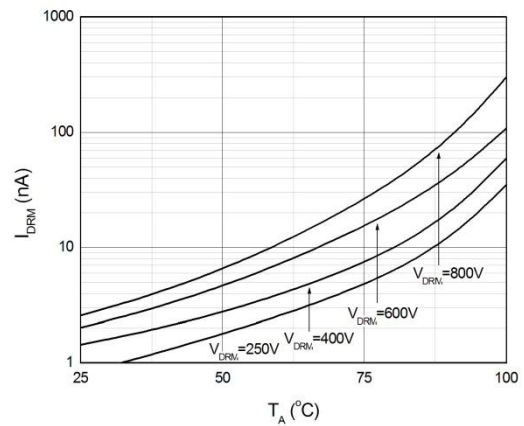


Fig.5 Normalized Off-state Terminal Voltage vs. Ambient Temperature

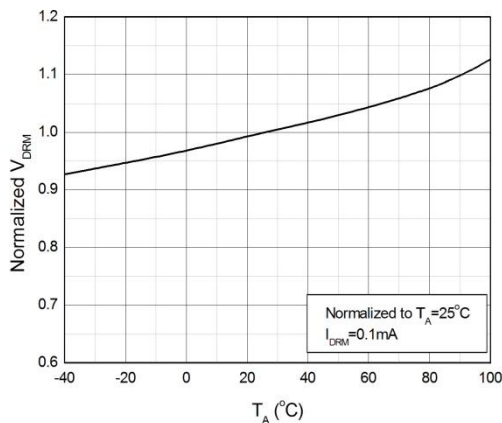
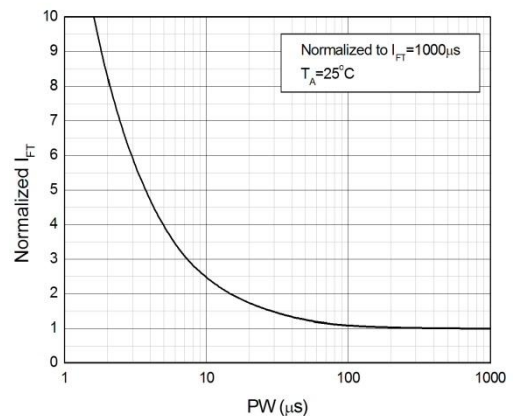


Fig.6 Normalized Trigger Current vs. LED Trigger Pulse Width



CHARACTERISTIC CURVES

Fig.7 Normalized Trigger Current vs. Ambient Temperature

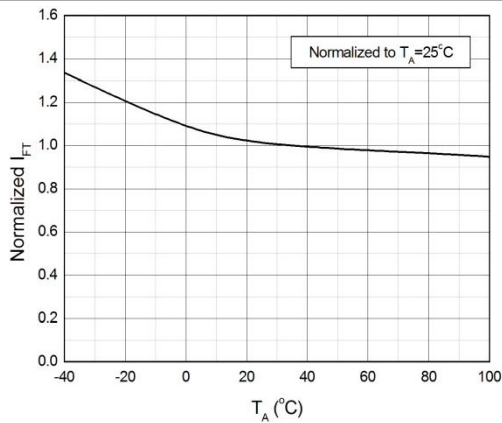


Fig.8 On-state Terminal Voltage vs. Ambient Temperature

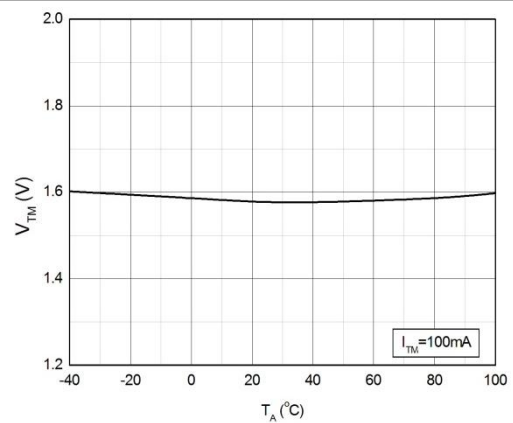


Fig.9 On-state Terminal Voltage vs. On-state Terminal Current

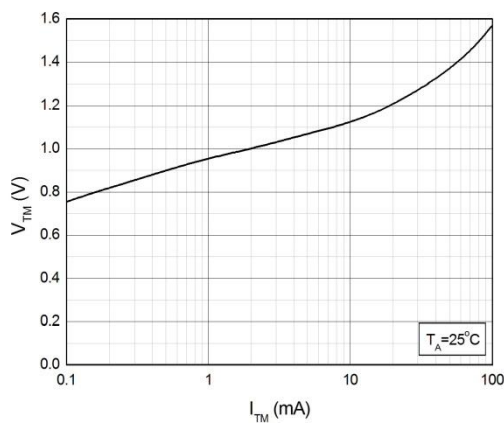


Fig.10 Holding Current vs. Ambient Temperature

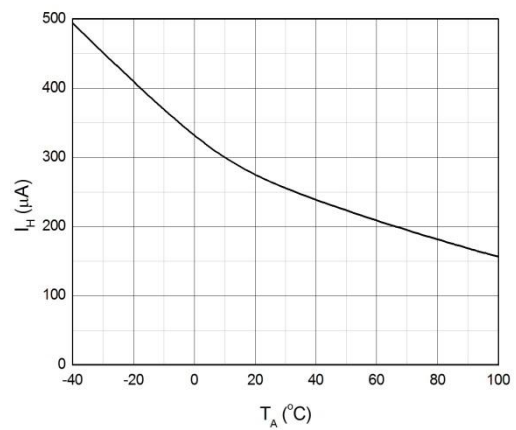


Fig.11 Turn On Time vs. Forward Current

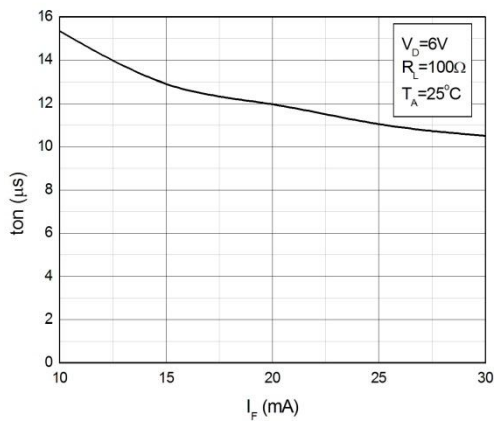
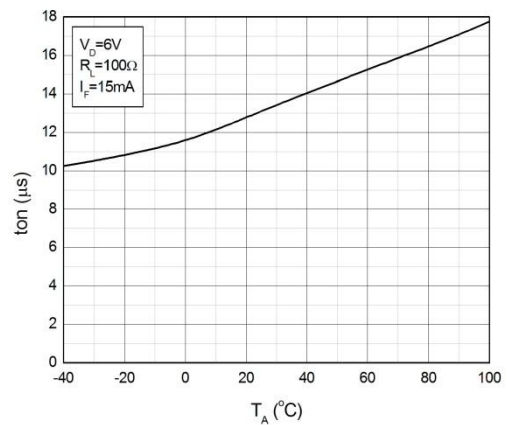


Fig.12 Turn On Time vs. Ambient Temperature



TEST CIRCUITS

Fig.13 Test Circuits of Turn On Time

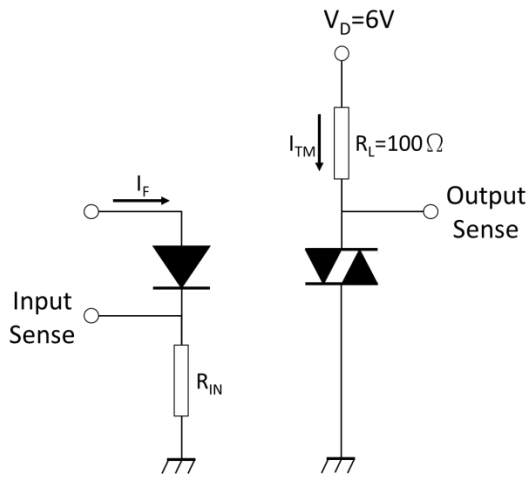


Fig.14 Waveforms of Turn On Time

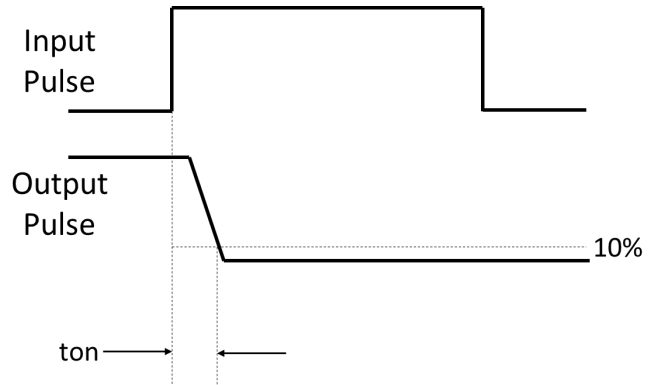


Fig.15 Test Circuits of dV/dt

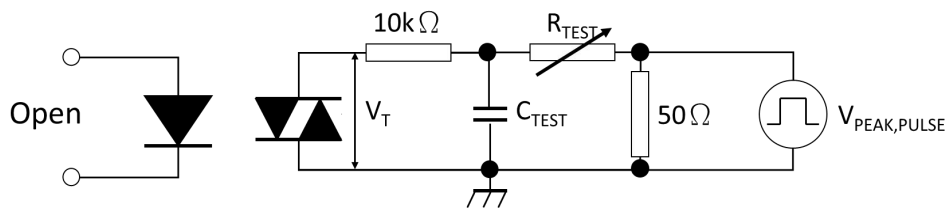
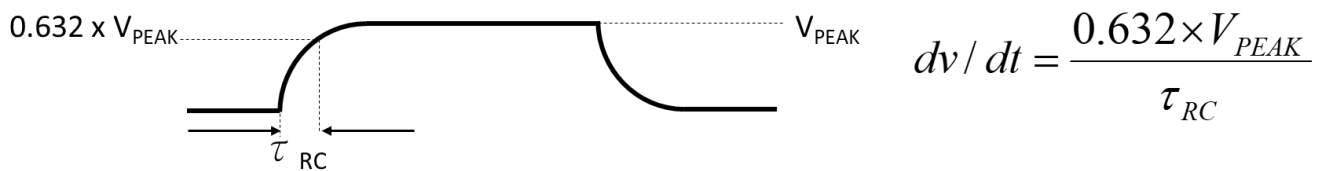
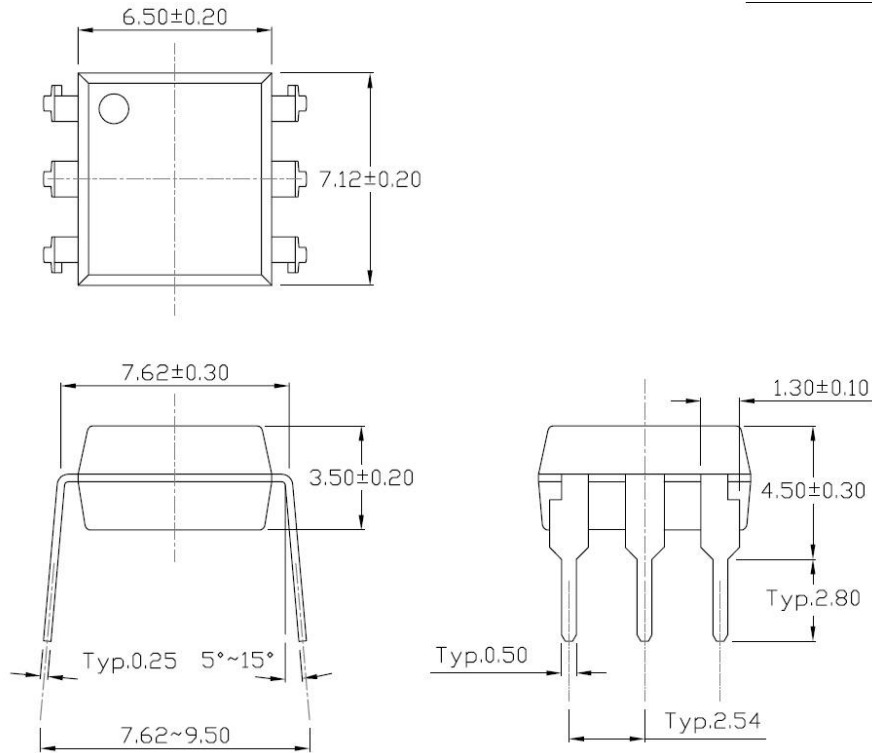


Fig.16 Waveforms of dV/dt

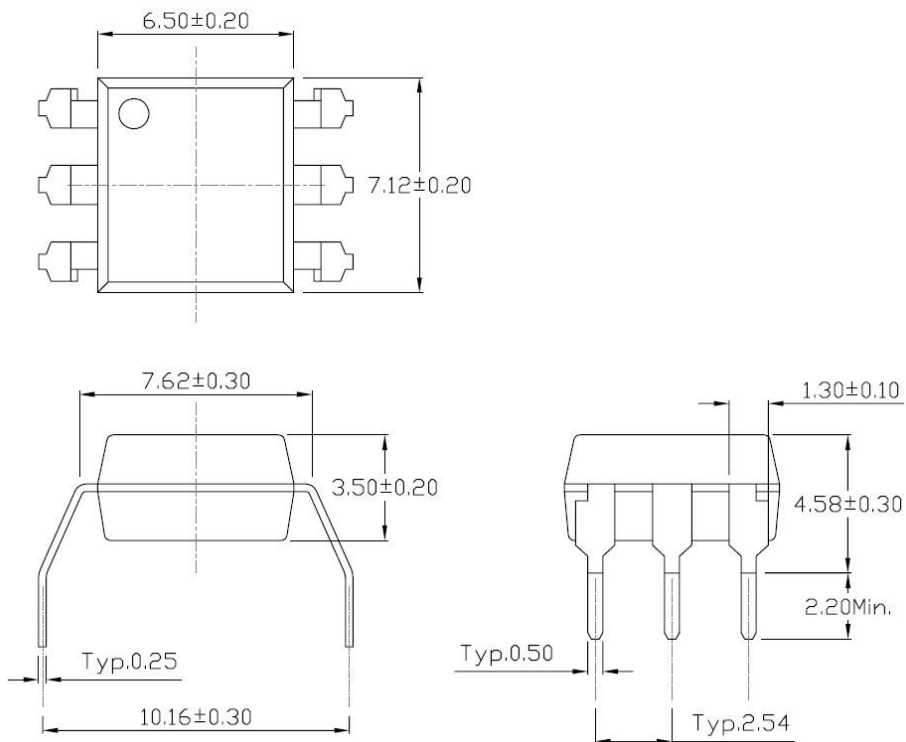


PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Standard DIP – Through Hole (DIP Type)

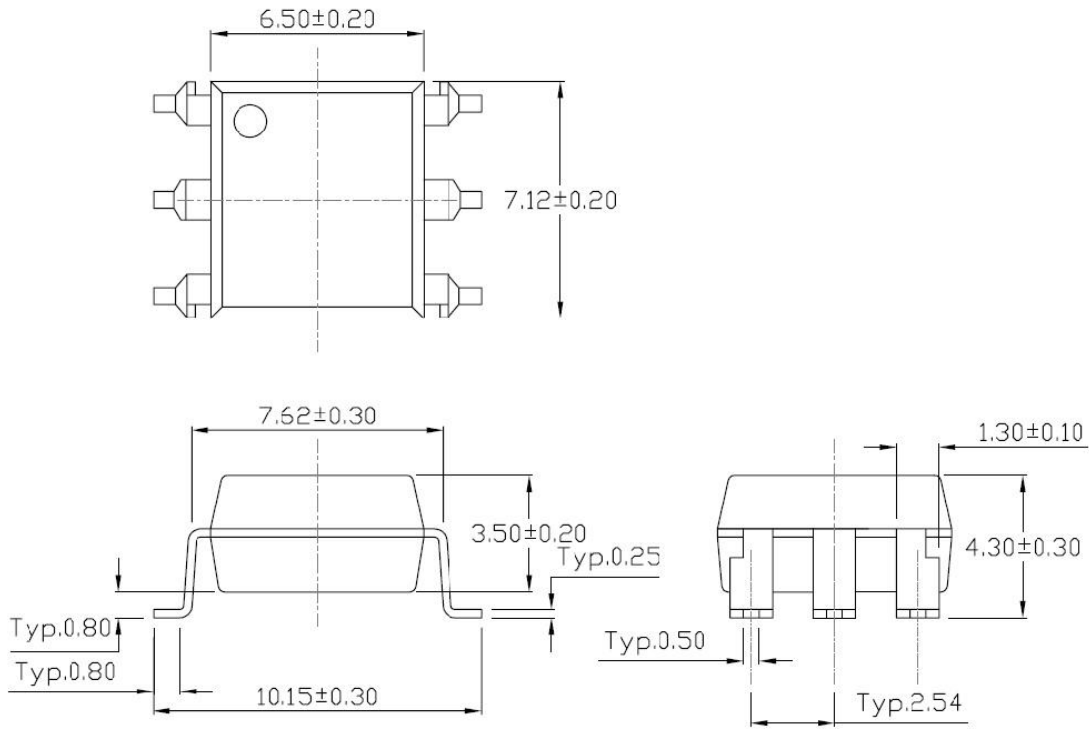


Gullwing (400mil) Lead Forming – Through Hole (M Type)

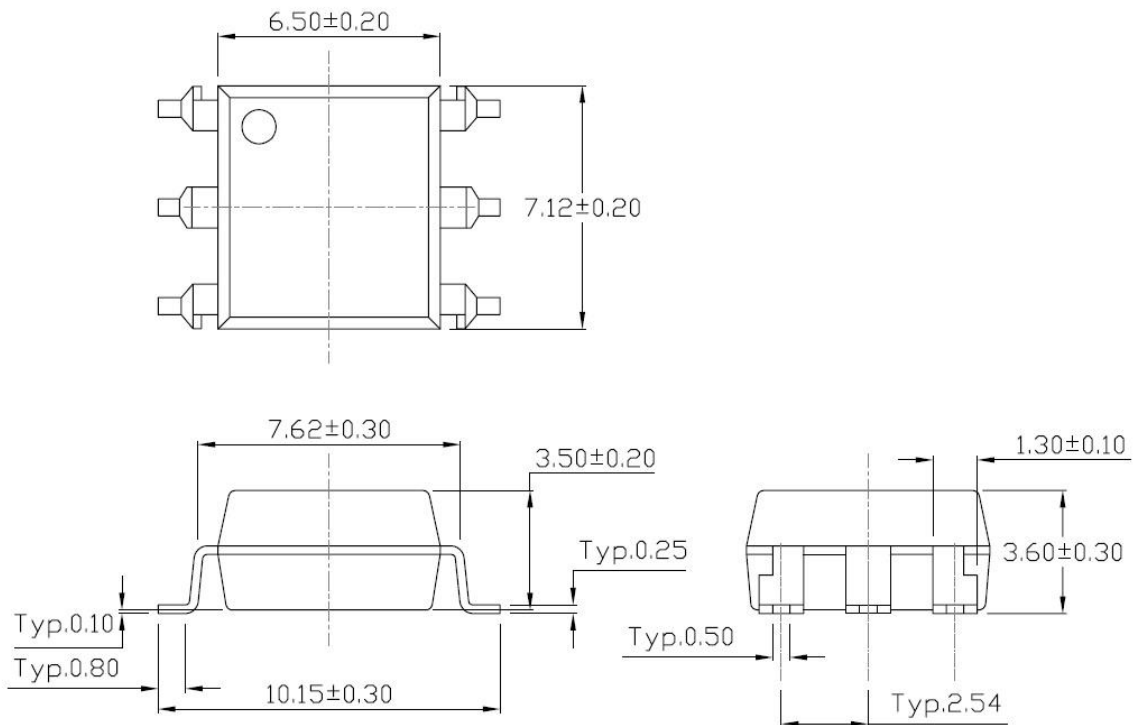


PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming (S Type)

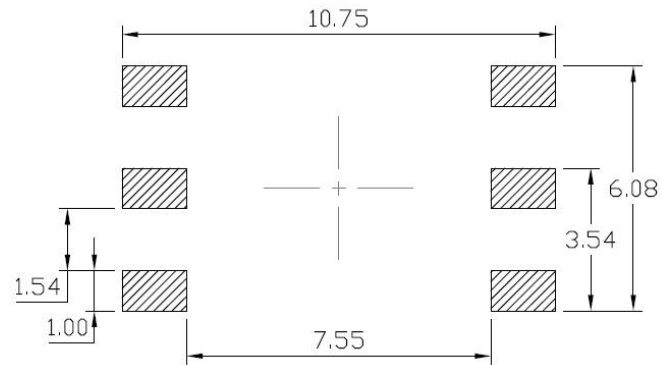


Surface Mount (Low Profile) Lead Forming (SL Type)

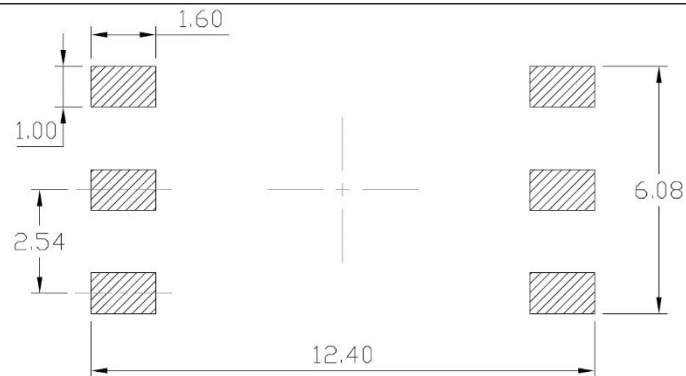


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming

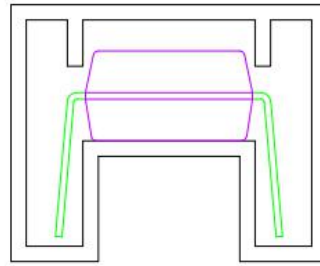
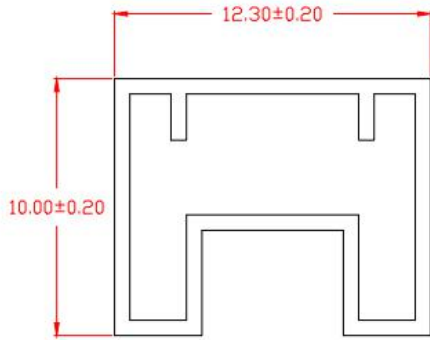


Surface Mount (Gullwing) Lead Forming



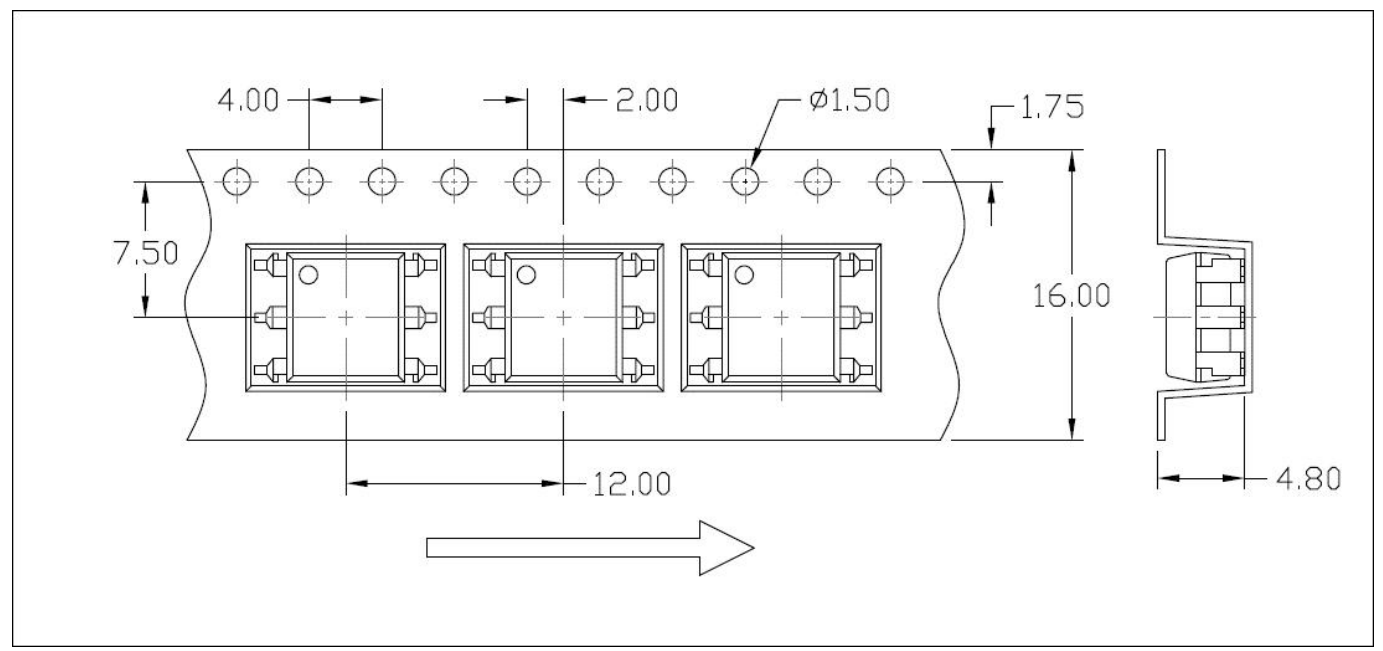
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

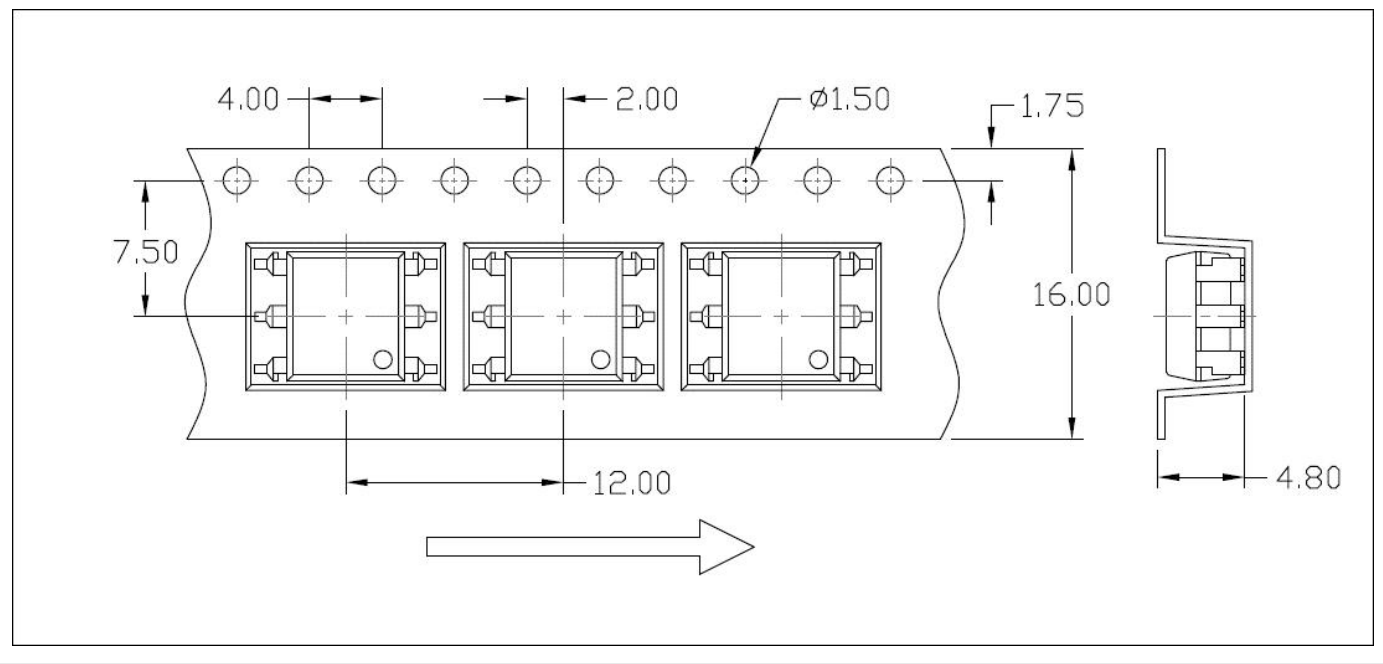


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1) & SL(T1)

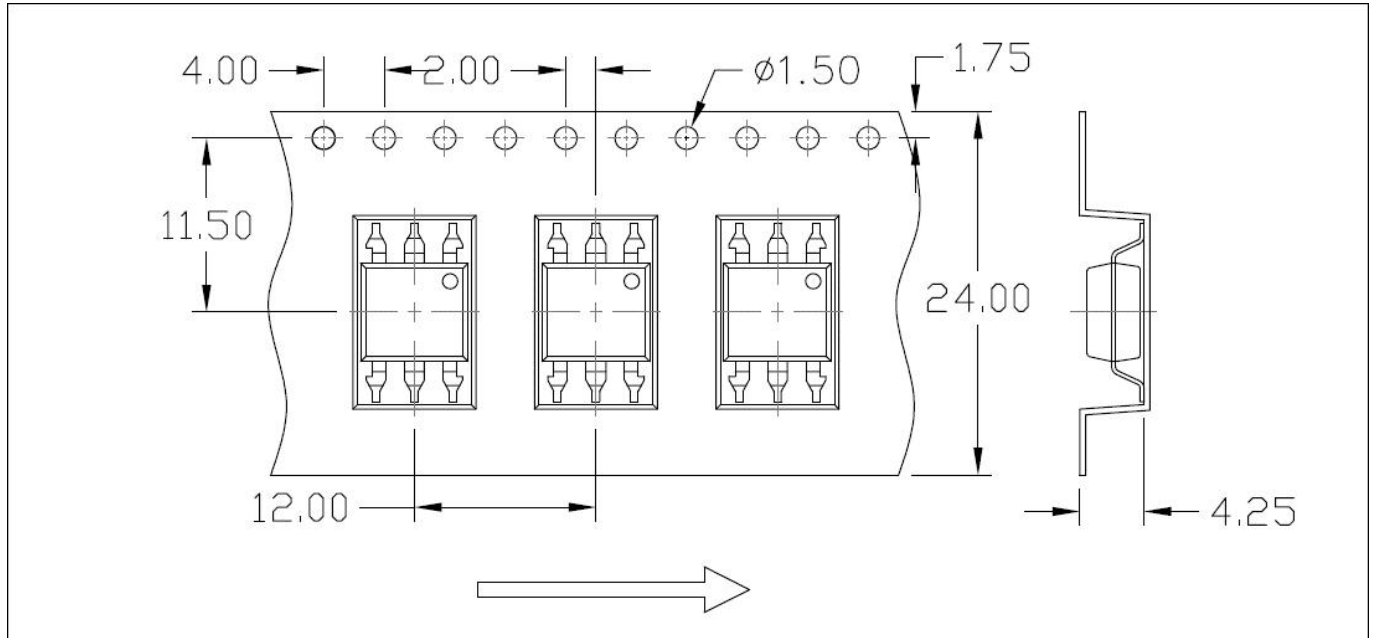


Option S(T2) & SL(T2)

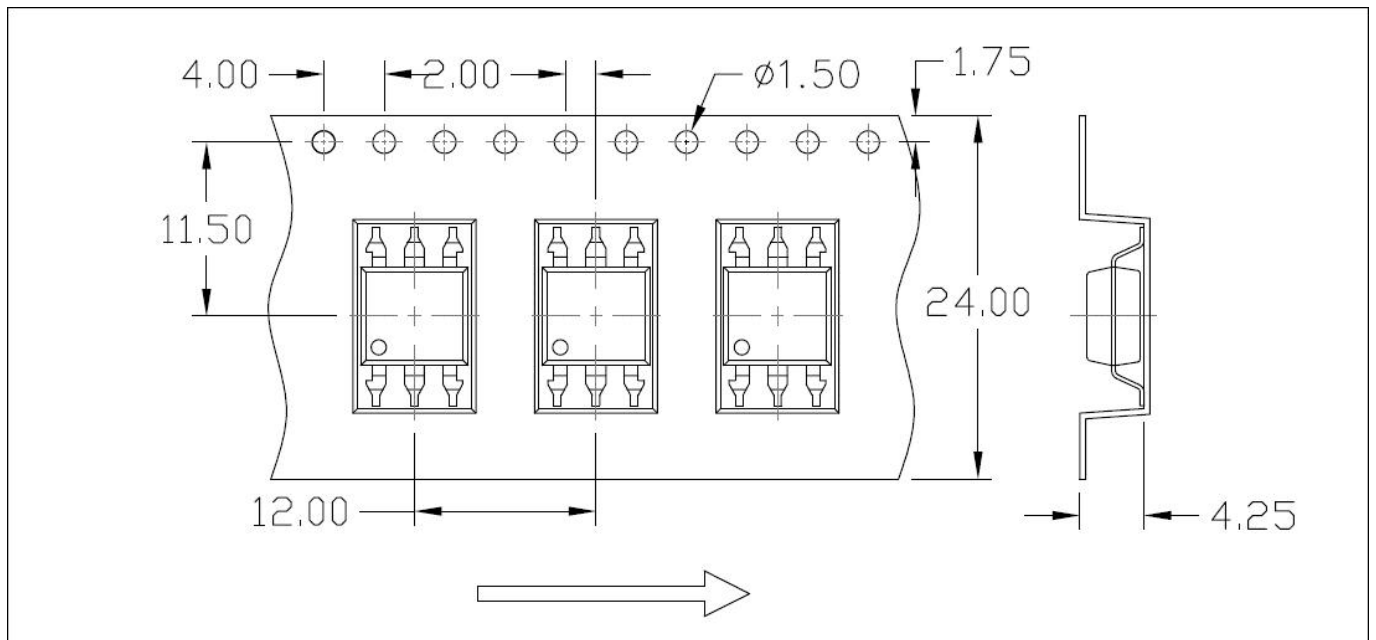


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option SLM(T1)

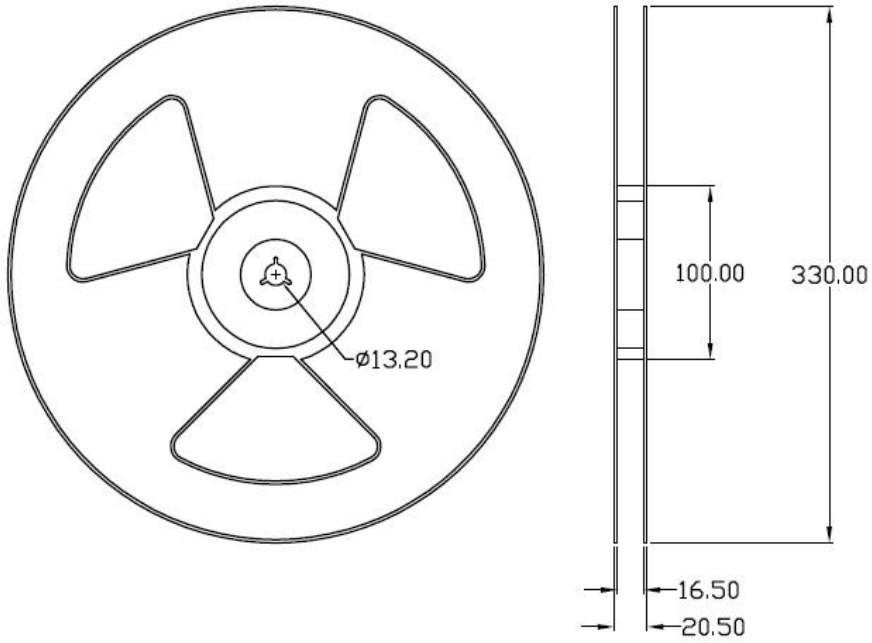


Option SLM(T2)

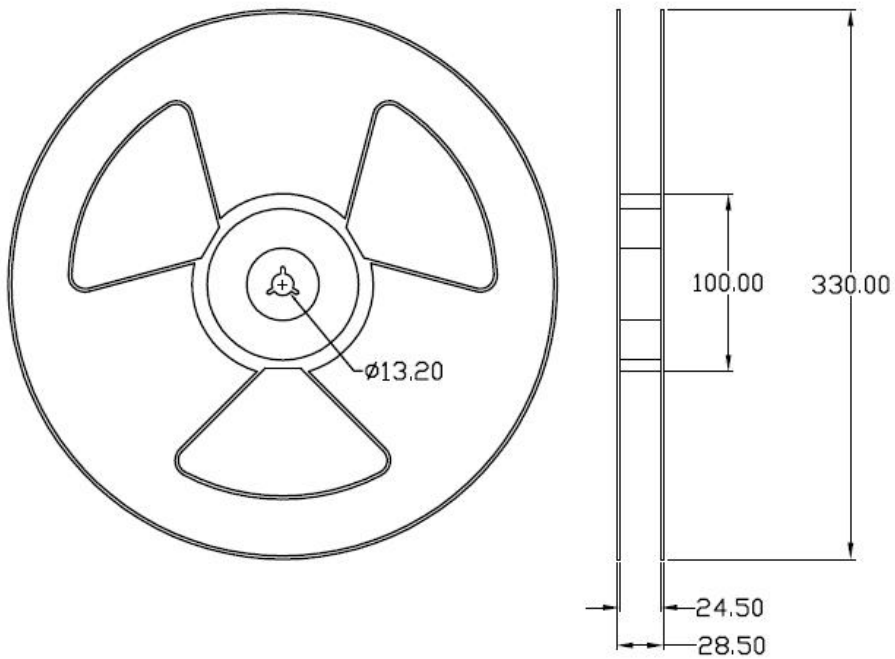


REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S & Option SL

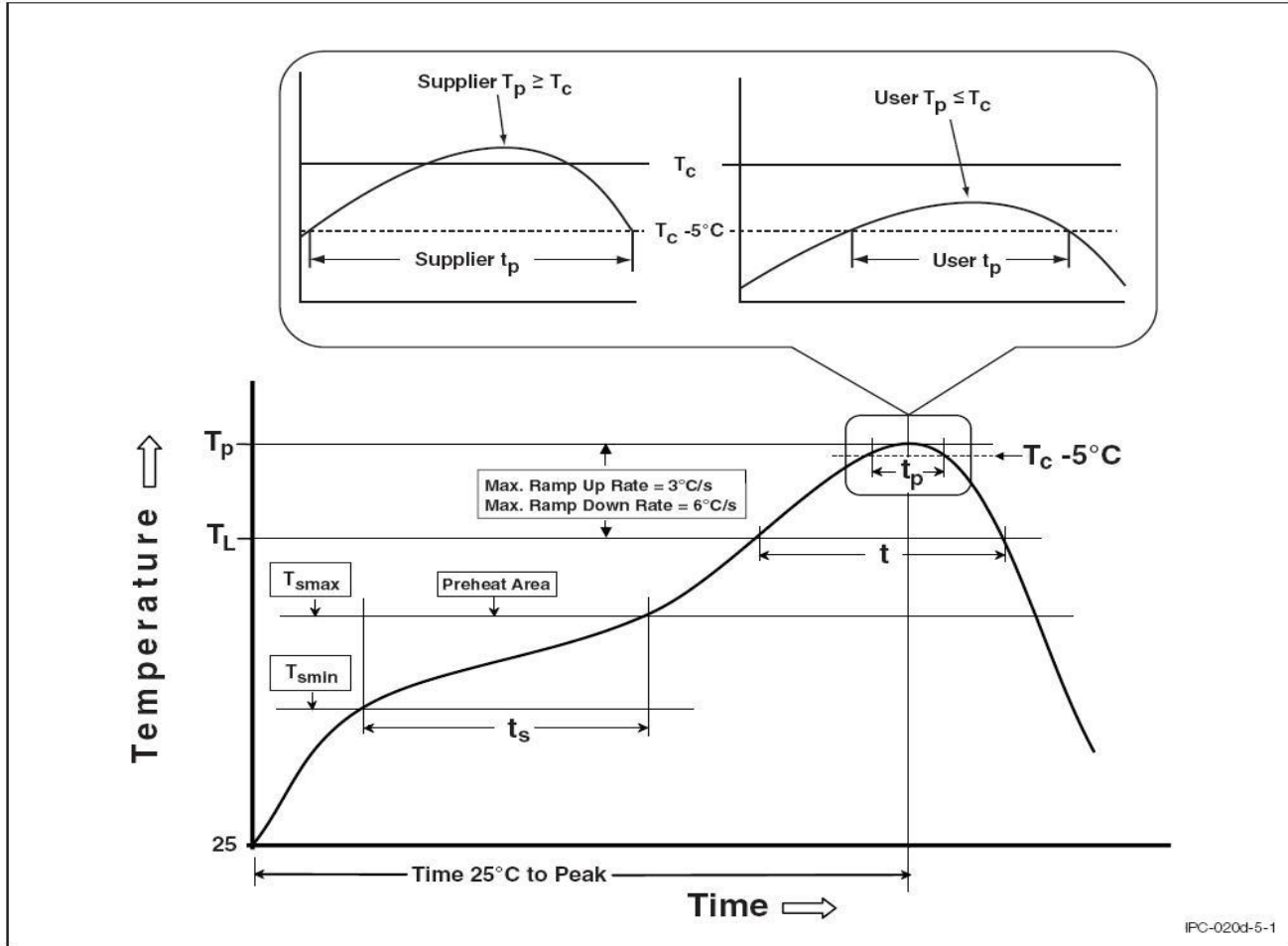


Option SLM



REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{min})	100	150°C
Temperature Max. (T _{max})	150	200°C
Time (t _s) from (T _{min} to T _{max})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.